

DATA SHEET

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74ABT245

Octal transceiver with direction pin
(3-State)

Product specification
Supersedes data of 1996 Sep 10
IC23 Data Handbook

1998 Jan 16

Octal transceiver with direction pin (3-State)

74ABT245

FEATURES

- Octal bidirectional bus interface
- 3-State buffers
- Output capability: +64mA/−32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 833 Method 3015 and 200 V per Machine Model
- Power-up 3-State
- Live insertion/extraction permitted
- Inputs are disabled during 3-State mode

DESCRIPTION

The 74ABT245 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT245 device is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The control function implementation minimizes external timing requirements. The device features an Output Enable (\overline{OE}) input for easy cascading and a Direction (DIR) input for direction control.

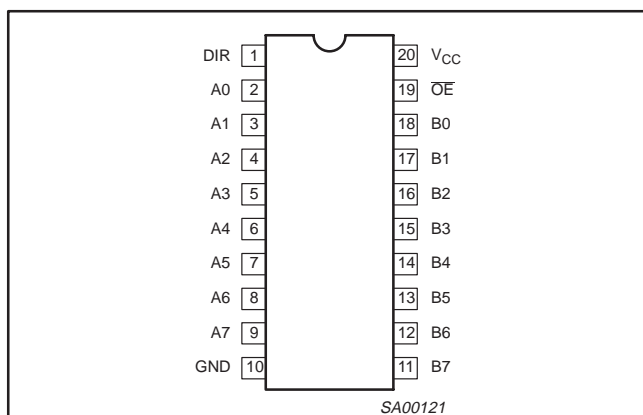
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}\text{C}; \text{GND} = 0\text{V}$	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay An to Bn or Bn to An	$C_L = 50\text{pF}; V_{CC} = 5\text{V}$	2.2 2.9	ns
C_{IN}	Input capacitance DIR, \overline{OE}	$V_I = 0\text{V}$ or V_{CC}	4	pF
$C_{I/O}$	I/O pin capacitance	Outputs disabled; $V_O = 0\text{V}$ or V_{CC}	7	pF
I_{CCZ}	Total supply current	Outputs disabled; $V_{CC} = 5.5\text{V}$	50	μA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	−40°C to +85°C	74ABT245 N	74ABT245 N	SOT146-1
20-Pin plastic SO	−40°C to +85°C	74ABT245 D	74ABT245 D	SOT163-1
20-Pin Plastic SSOP Type II	−40°C to +85°C	74ABT245 DB	74ABT245 DB	SOT339-1
20-Pin Plastic TSSOP Type I	−40°C to +85°C	74ABT245 PW	74ABT245PW DH	SOT360-1

PIN CONFIGURATION



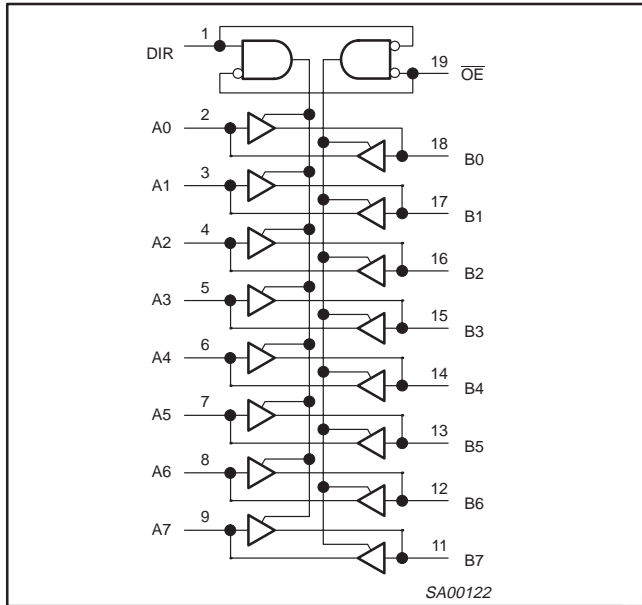
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	DIR	Direction control input
2, 3, 4, 5, 6, 7, 8, 9	A0 – A7	Data inputs/outputs (A side)
18, 17, 16, 15, 14, 13, 12, 11	B0 – B7	Data inputs/outputs (B side)
19	\overline{OE}	Output enable input (active-Low)
10	GND	Ground (0V)
20	V_{CC}	Positive supply voltage

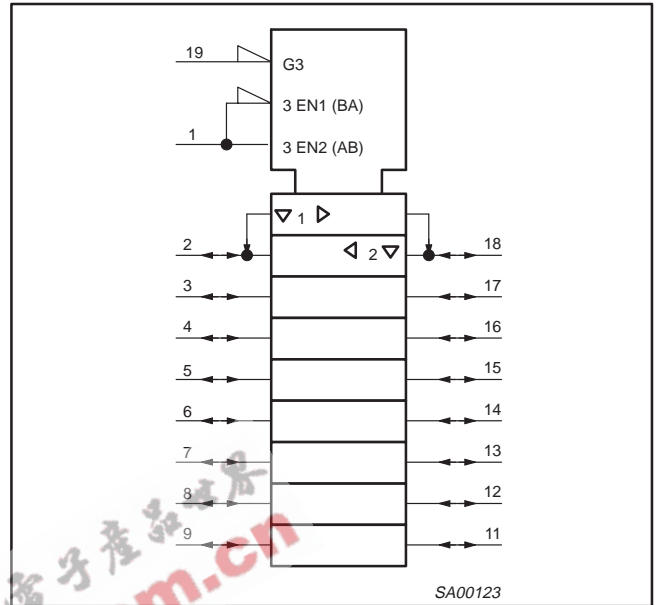
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LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPUTS		INPUTS/OUTPUTS	
OE	DIR	An	Bn
L	L	An = Bn	Inputs
L	H	Inputs	Bn = An
H	X	Z	Z

H = High voltage level
 L = Low voltage level
 X = Don't care
 Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-18	mA
V _I	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
I _{OUT}	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level Input voltage		0.8	V
I_{OH}	High-level output current		-32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	5	ns/V
T_{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			$T_{amb} = +25^\circ\text{C}$			$T_{amb} = -40^\circ\text{C}$ to $+85^\circ\text{C}$		
			Min	Typ	Max	Min	Max	
V_{IK}	Input clamp voltage	$V_{CC} = 4.5\text{V}; I_{IK} = -18\text{mA}$		-0.9	-1.2		-1.2	V
V_{OH}	High-level output voltage	$V_{CC} = 4.5\text{V}; I_{OH} = -3\text{mA}; V_I = V_{IL}$ or V_{IH}	2.5	2.9		2.5		V
		$V_{CC} = 5.0\text{V}; I_{OH} = -3\text{mA}; V_I = V_{IL}$ or V_{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5\text{V}; I_{OH} = -32\text{mA}; V_I = V_{IL}$ or V_{IH}	2.0	2.4		2.0		V
V_{OL}	Low-level output voltage	$V_{CC} = 4.5\text{V}; I_{OL} = 64\text{mA}; V_I = V_{IL}$ or V_{IH}		0.42	0.55		0.55	V
I_I	Input leakage current	Control pins $V_{CC} = 5.5\text{V}; V_I = \text{GND}$ or 5.5V		± 0.01	± 1.0		± 1.0	μA
		Data pins $V_{CC} = 5.5\text{V}; V_I = \text{GND}$ or 5.5V		± 5	± 100		± 100	μA
I_{OFF}	Power-off leakage current	$V_{CC} = 0.0\text{V}; V_I$ or $V_O \leq 4.5\text{V}$		± 5.0	± 100		± 100	μA
I_{PU}/I_{PD}	Power-up/down 3-State output current ³	$V_{CC} = 2.0\text{V}; V_O = 0.5\text{V}; V_I = \text{GND}$ or V_{CC} ; $V_{OE} = \text{Don't care}$		± 5.0	± 50		± 50	μA
$I_{IH} + I_{OZH}$	3-State output High current	$V_{CC} = 5.5\text{V}; V_O = 2.7\text{V}; V_I = V_{IL}$ or V_{IH}		5.0	50		50	μA
$I_{IL} + I_{OZL}$	3-State output Low current	$V_{CC} = 5.5\text{V}; V_O = 0.5\text{V}; V_I = V_{IL}$ or V_{IH}		-5.0	-50		-50	μA
I_{CEX}	Output high leakage current	$V_{CC} = 5.5\text{V}; V_O = 5.5\text{V}; V_I = \text{GND}$ or V_{CC}		5.0	50		50	μA
I_O	Output current ¹	$V_{CC} = 5.5\text{V}; V_O = 2.5\text{V}$	-40	-100	-180	-40	-180	mA
I_{CCH}	Quiescent supply current	$V_{CC} = 5.5\text{V}; \text{Outputs High}, V_I = \text{GND}$ or V_{CC}		50	250		250	μA
I_{CCL}		$V_{CC} = 5.5\text{V}; \text{Outputs Low}, V_I = \text{GND}$ or V_{CC}		24	30		30	mA
I_{CCZ}		$V_{CC} = 5.5\text{V}; \text{Outputs 3-State}; V_I = \text{GND}$ or V_{CC}		50	250		250	μA
ΔI_{CC}	Additional supply current per input pin ²	Outputs enabled, one input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5\text{V}$		0.5	1.5		1.5	mA
		Outputs 3-State, one data input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5\text{V}$		50	250		250	μA
		Outputs 3-State, one enable input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5\text{V}$		0.5	1.5		1.5	mA

NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input at 3.4V.
- This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. For $V_{CC} = 2.1\text{V}$ to $V_{CC} = 5\text{V} \pm 10\%$, a transition time of up to 100 μsec is permitted.

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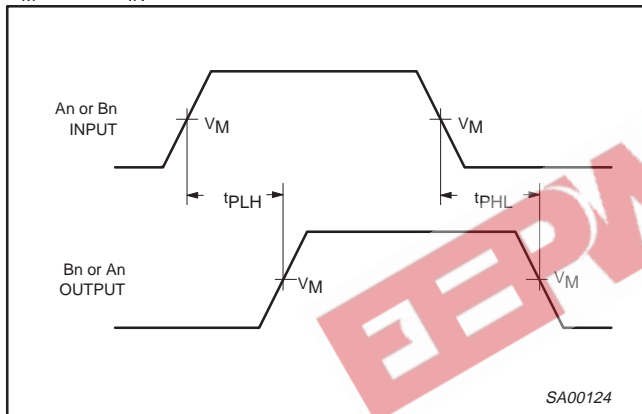
AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5\text{ns}$; $C_L = 50\text{pF}$, $R_L = 500\Omega$

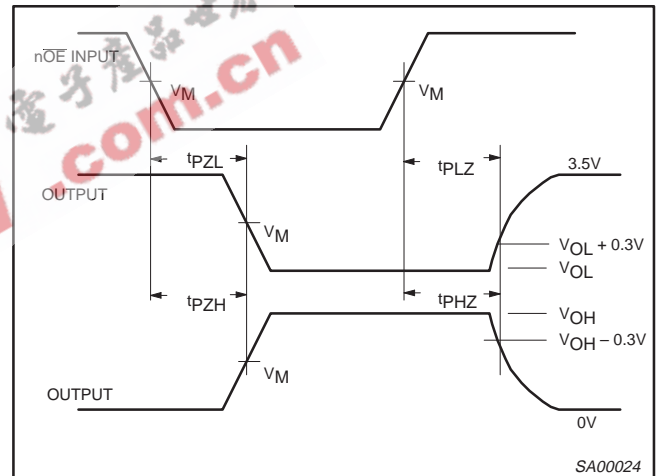
SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			$T_{\text{amb}} = +25^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V}$			$T_{\text{amb}} = -40^\circ\text{C to } +85^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V} \pm 0.5\text{V}$		
			Min	Typ	Max	Min	Max	
t_{PLH} t_{PHL}	Propagation delay An to Bn or Bn to An	1	1.0 1.0	2.2 2.9	4.1 4.2	1.0 1.0	4.6 4.6	ns
t_{PZH} t_{PZL}	Output enable time to High and Low level	2	1.3 2.3	3.0 4.0	4.8 5.8	1.3 2.3	5.3 6.3	ns
t_{PHZ} t_{PLZ}	Output disable time from High and Low Level	2	1.0 1.0	4.7 4.1	6.2 5.8	1.0 1.0	7.2 6.3	ns

AC WAVEFORMS

$V_M = 1.5\text{V}$, $V_{\text{IN}} = \text{GND to } 3.0\text{V}$

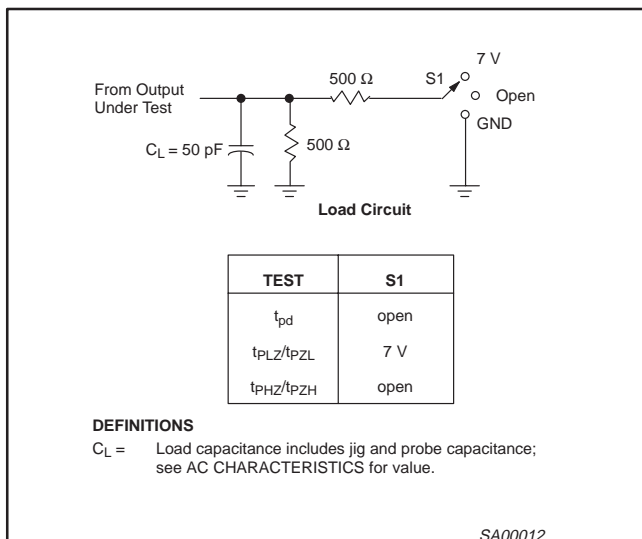


Waveform 1. Waveforms Showing the Input to Output Propagation Delays



Waveform 2. Waveforms Showing the 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS

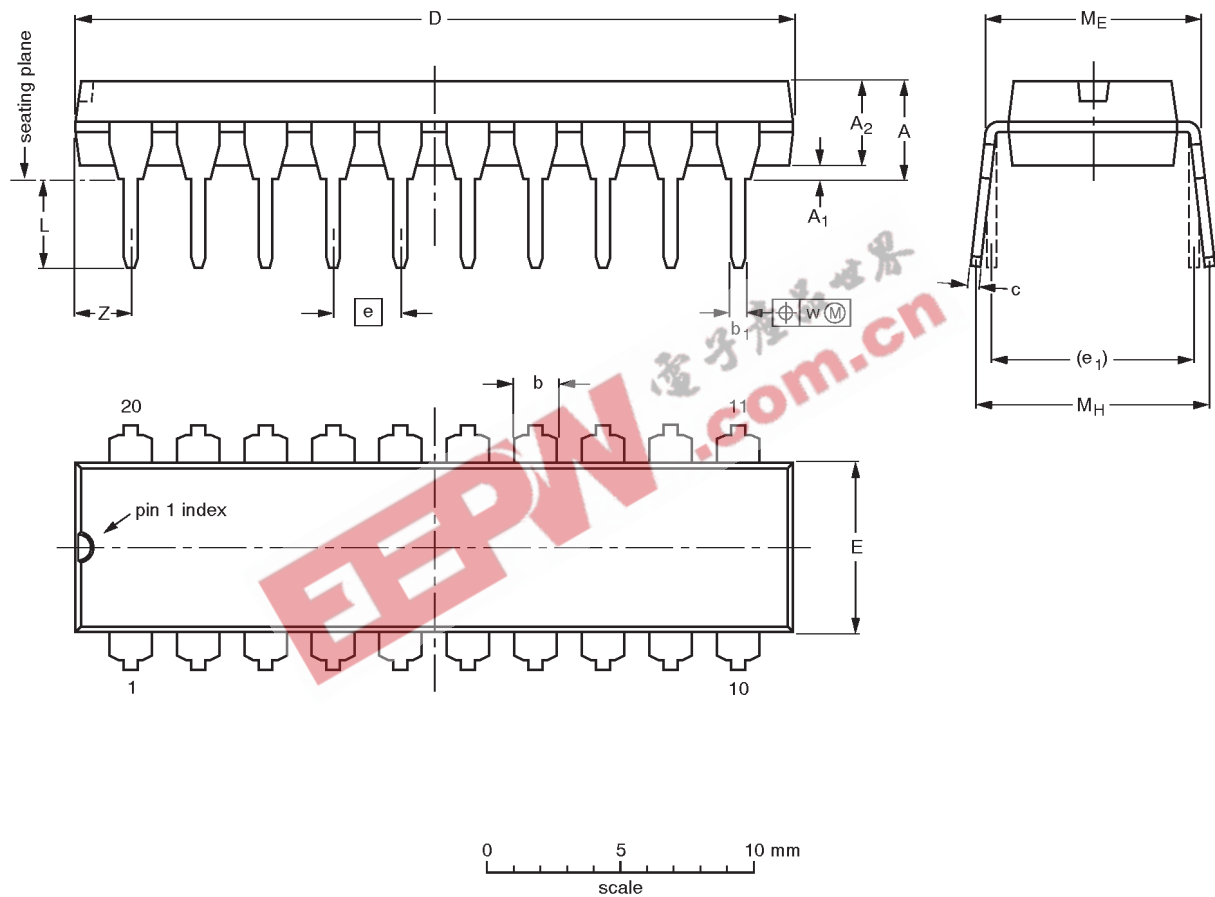


Octal transceiver with direction pin (3-State)

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

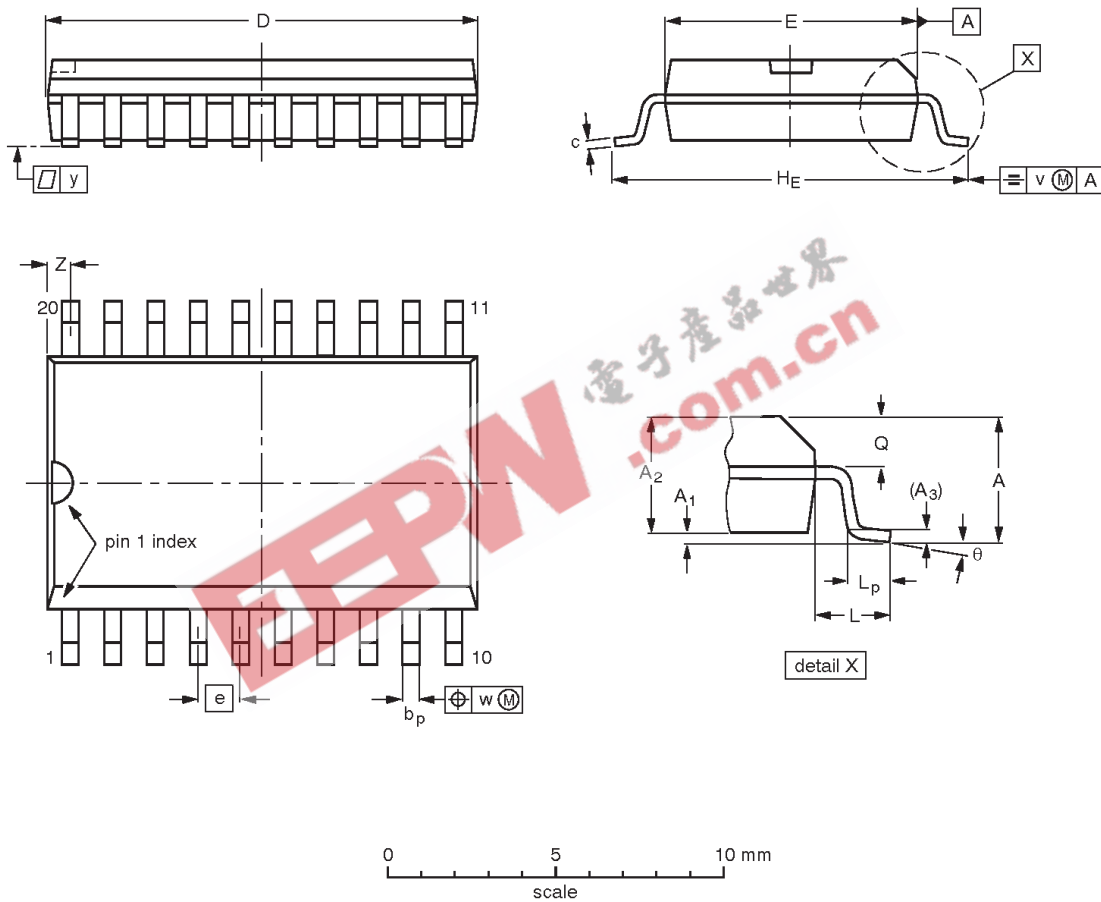
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

Octal transceiver with direction pin (3-State)

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

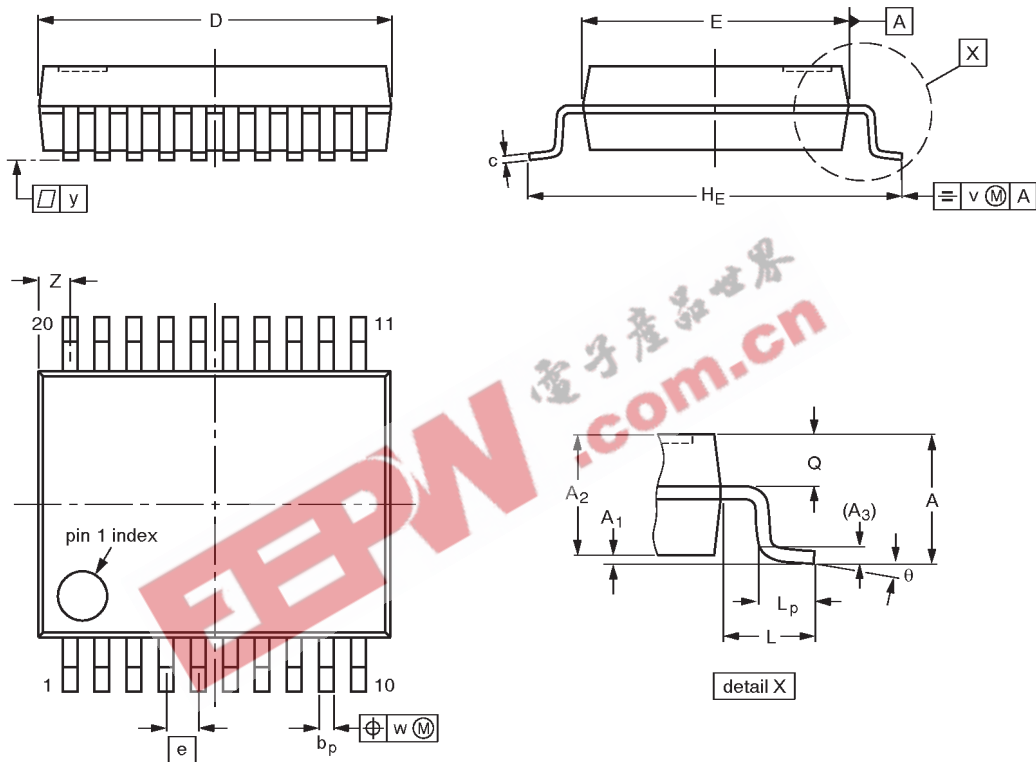
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

Octal transceiver with direction pin (3-State)

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

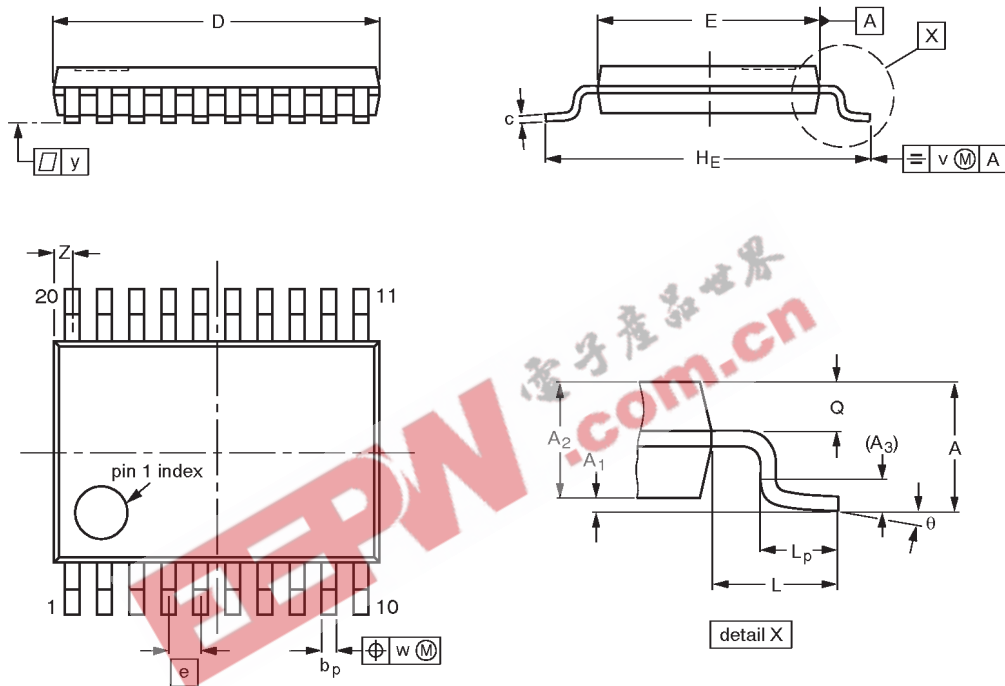
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				93-09-08 95-02-04

Octal transceiver with direction pin (3-State)

74ABT245

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				93-06-16 95-02-04

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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